SPECIFICATION

PRODUCT: CERAMIC RESONATOR

MODEL: ZTACC .. MG



SHOULDER ELECTRONICS LIMITED

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1. Scope

The specification is fit for ceramic resonator 1.84-8.00MHz.

2. Part Number: ZTACC .. MG

3. Electrical Characteristics

| No. | ltem | Characteristics | | | | |
|------|---|-----------------|--|--|--|--|
| 3-1 | Oscillate Frequency (MHz) | 1.84-8.00 | | | | |
| 3.2 | Frequency Tolerance max | ±0.5% | | | | |
| 3.3 | Resonant Impedance max (Ω) | 100 | | | | |
| 3.4 | Built – in Capacitance (PF) | | | | | |
| 3.5 | Insulate Resistance min (M Ω) | 100 | | | | |
| 3.6 | Withstanding Voltage D.C (V) | 100(max 5 sec) | | | | |
| 3.7 | Voltage (1) D.C Voltage max(V) (2) Input Voltage max(V) | 6 15Vp-p | | | | |
| 3.8 | Temp characteristics of Oscillate frequency max | ±0.3% | | | | |
| 3.9 | Operating Temp Range("C) | -20 ~ +80 | | | | |
| 3.10 | Storage Temp (°C) | -55 ~ +85 | | | | |

4. Test Circuit



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5. Dimension



6. Physical and Environmental Characteristics

| No | ltem | Condition of Test | Performance Requirements | | | | |
|-----|---------------------|--|---|--|--|--|--|
| 6.1 | Humidity | Keep the resonator at 40 ± 2 °C and 90-95% RH for 96 ± 4 hours. Then release the resonator into the room condition for 1 hour prior to the measurement. | It shall fulfill the specifications in Table 1. | | | | |
| 6.2 | Vibration | Subject the resonator to vibration for 2 hours each in x,y and z axis with the amplitude of 1.5mm, the frequency shall be varied uniformly between the limits of 10-55Hz | It shall fulfill the specifications in Table 1. | | | | |
| 6.3 | Mechanical Shock | Drop the resonator randomly onto a concrete floor from the height of 100 cm 3 times. | It shall fulfill the specifications in Table 1. | | | | |
| 6.4 | Soldering Test | Passed through the re-flow oven under the following condition and left at room temperature for 1 hour before measurement. | It shall fulfill the specifications in Table 1. | | | | |

| | | Temperature at surface of the substrate | Time | | |
|-----|---------------------------------|---|---|--|--|
| | | Preheat 150±5℃ | 60±10 sec. | | |
| | | Peak 240±5 ℃ | 10±3 sec. | | |
| 6.5 | Solder Ability | Dip the resonator solder bath at 230 | More than 95% of the terminal surface shall be covered. | | |
| 6.6 | High Temperature Exposure | Subject the resona \pm 4 hours. Then r into the room condito the measurement | It shall fulfill the specifications in Table 1. | | |
| 6.7 | Low Temperature | Subject the resonat ± 4 hours. Then r into the room condition to the measurement | It shall fulfill the specifications in Table 1. | | |
| 6.8 | Temperature Cycling | Subject the resonant minutes followed b of 85 °C for 30 m repeated 5 times w 15 second at the hour prior to the me | It shall fulfill the specifications in Table 1. | | |

TABLE1

| Item | Specification | | | | |
|------------------------------|----------------|--|--|--|--|
| Oscillation Frequency Change | ∆F/Fo≪0.3% max | | | | |
| Resonant Impedance | ∆Ro≼±10 Ohm | | | | |

7.

RECOMMENDED REFLOW SOLDERING STANDARD CONDITIONS





8. Packing



Tape Dimension (mm)

| | A ±0.2 | В ±0.2 | C ±0.3 | D ±0.1 | Е ±0.1 | F 土0.1 | G ±0.1 | H ±0.1 | ØJ ±0.1 | ØN ±0.1 | M max | R max | К ±0.2 | T ±0.1 |
|----|-----------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|------------|------------|-------------|----------|-----------|-----------|
| MG | 3.8 | 7.8 | 16.0 | 7.5 | | | | | | | | | 2.1 | |
| MT | 5.0 | 4.4 | 12.0 | 5.5 | 1.75 | 8.0 | 4.0 | 2.0 | 1.5 | 1.6 | 10 " | 0.3 | 1.8 | 0.3 |
| MX | 3.4 | 4.0 | 12.0 | 5.5 | | | | | | | | | 1.3 | |

Standard Package: 4Kpcs / reel